

## 250W FLIP CHIP TVS ARRAY

### DESCRIPTION

The P0404FCxxC Series Flip Chips employ advanced silicon P/N junction technology for unmatched board-level transient voltage protection against Electrostatic Discharge (ESD) and Electrical Fast Transients (EFT). Developed specifically for high-density circuit protection, this series meets the IEC 61000-4-2 and 61000-4-4 requirements. These devices are ideally suited for handheld devices, PCMCIA and SMART cards.

This series provides ESD protection greater than 25 kilovolts with a peak pulse power dissipation of 250 Watts per line for an 8/20 $\mu$ s waveform. In addition, the P0404FCxxC series features superior clamping performance, low leakage current characteristics and a response time of less than a nanosecond. Their low inductance virtually eliminates overshoot voltage due to package inductance.

### FEATURES

- Compatible with IEC 61000-4-2 (ESD): Air 15kV, Contact 8kV
- Compatible with IEC 61000-4-4 (EFT): 40A, 5/50ns
- ESD Protection > 25 kilovolts
- Available in Voltages Ranging from 3.3V to 36V
- 250 Watts Peak Pulse Power per Line (tp = 8/20 $\mu$ s)
- Bidirectional Configuration & Monolithic Structure
- Protection for 1 to 3 Lines
- RoHS Compliant
- REACH Compliant

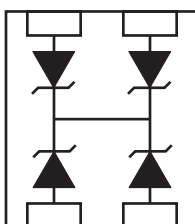
### APPLICATIONS

- SMART Phones
- MCM Boards
- Wireless Communication Circuits
- IR LEDs
- SMART & PCMCIA Cards

### MECHANICAL CHARACTERISTICS

- Standard EIA Chip Size: 0404
- Approximate Weight: 0.73 milligrams
- Lead-Free Plating
- Solder Reflow Temperature:
  - Lead-Free - Sn/Ag/Cu, 96/3.5/0.5: 260-270°C
- Flammability Rating UL 94V-0
- 8mm Tape per EIA Standard 481
- Top Contacts: Solder Bump 0.004" in Height (Nominal)

### PIN CONFIGURATION



**TYPICAL DEVICE CHARACTERISTICS**
**MAXIMUM RATINGS @ 25°C Unless Otherwise Specified**

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P <sub>PP</sub>	250	Watts
Operating Temperature	T <sub>A</sub>	-55 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	°C

**ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified**

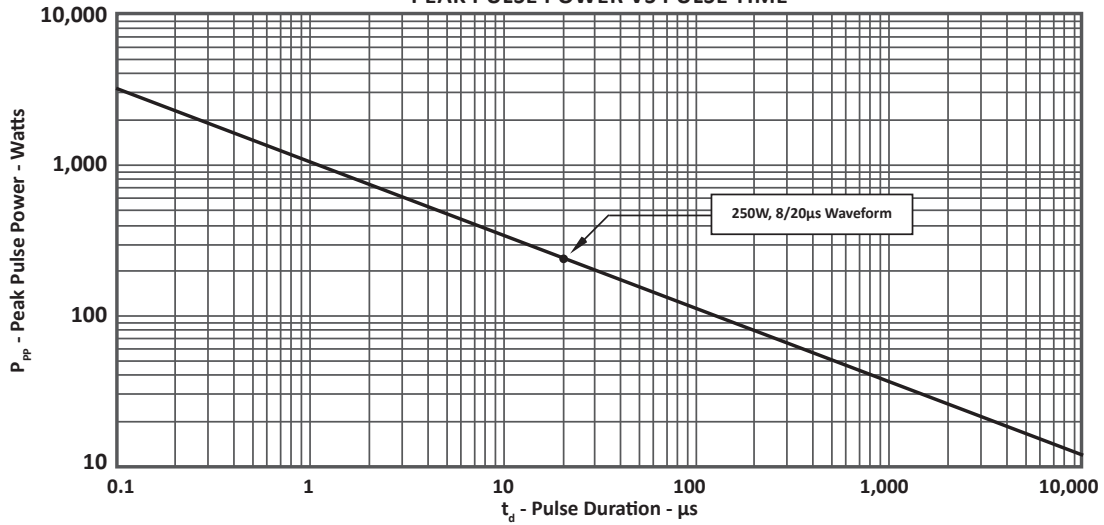
PART NUMBER (Note 1)	RATED STAND-OFF VOLTAGE  V <sub>WM</sub> VOLTS	MINIMUM BREAKDOWN VOLTAGE  @ 1mA V <sub>(BR)</sub> VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2)  @ I <sub>p</sub> = 1A V <sub>c</sub> VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2)  @ 8/20μS V <sub>c</sub> @ I <sub>PP</sub>	MAXIMUM LEAKAGE CURRENT (Note 2)  @ V <sub>WM</sub> I <sub>D</sub> μA	TYPICAL CAPACITANCE  @ 0V, 1MHz C pF
P0404FC3.3C	3.3	4.0	7.0	12.5V @ 20A	75*	150
P0404FC05C	5.0	6.0	11.0	14.7V @ 17A	10**	100
P0404FC08C	8.0	8.5	13.2	19.2V @ 13A	10***	75
P0404FC12C	12.0	13.3	19.8	29.7V @ 9A	1	50
P0404FC15C	15.0	16.7	25.4	35.7V @ 7A	1	40
P0404FC24C	24.0	26.7	37.2	55.0V @ 5A	1	30
P0404FC36C	36.0	40.0	60.0	70.0V @ 3A	1	25

**NOTES**

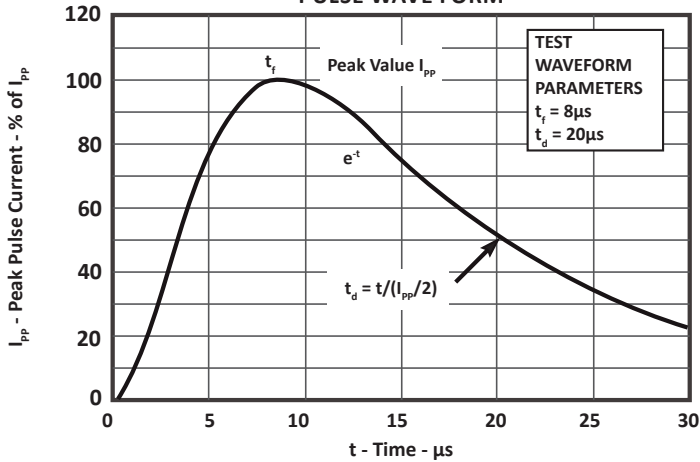
- All devices are bidirectional. Electrical characteristics apply in both directions.
- \*Maximum leakage current < 5μA @ 2.8V. \*\*Maximum leakage current < 500nA @ 3.3V. \*\*\*Maximum leakage current < 200nA @ 5V.

TYPICAL DEVICE CHARACTERISTICS

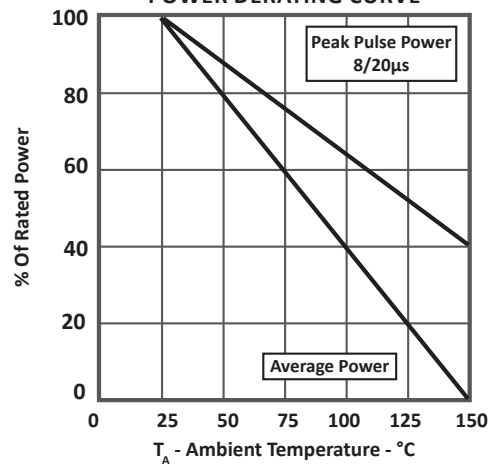
**FIGURE 1**  
PEAK PULSE POWER VS PULSE TIME



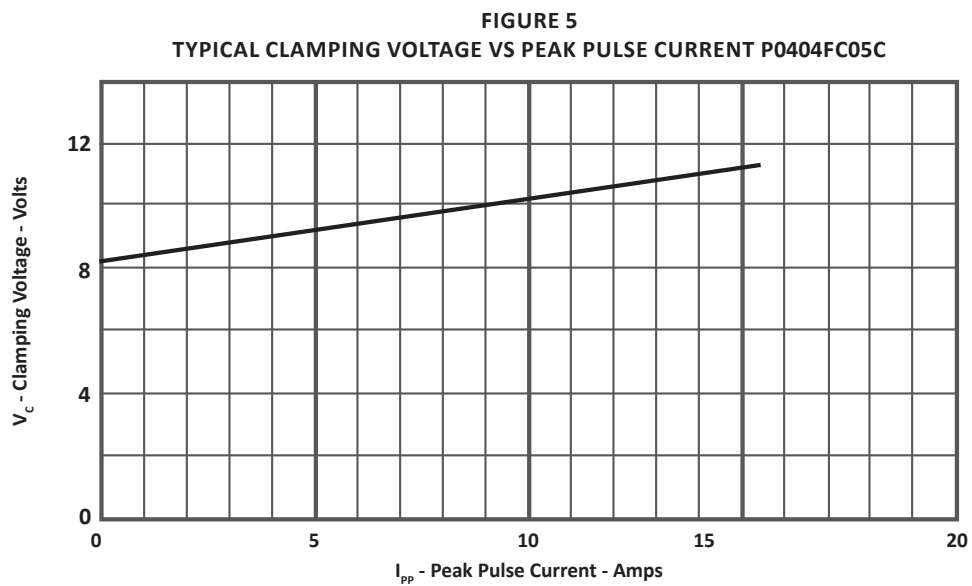
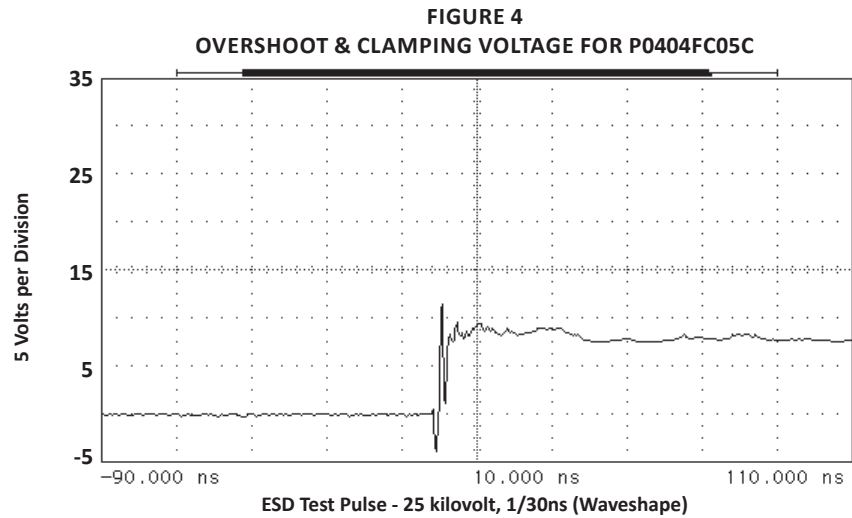
**FIGURE 2**  
PULSE WAVE FORM



**FIGURE 3**  
POWER DERATING CURVE



## TYPICAL DEVICE CHARACTERISTICS



## SOLDER REFLOW INFORMATION

PRINTED CIRCUIT BOARD RECOMMENDATIONS	
PARAMETER	VALUE
Pad Size on PCB	0.275mm
Pad Shape	Round
Pad Definition	Non-Solder Mask Defined Pads
Solder Mask Opening	0.325mm Round
Solder Stencil Thickness	0.150mm
Solder Stencil Aperture Opening (Laser cut, 5% tapered walls)	0.330mm Round
Solder Paste Type	No Clean
Pad Protective Finish	OSP (Entek Cu Plus 106A)
Tolerance - Edge To Corner Ball	±50µm
Solder Ball Side Coplanarity	±20µm
Maximum Dwell Time Above Liquidous (183°C)	60 seconds
Soldering Maximum Temperature	270°C

### REQUIREMENTS

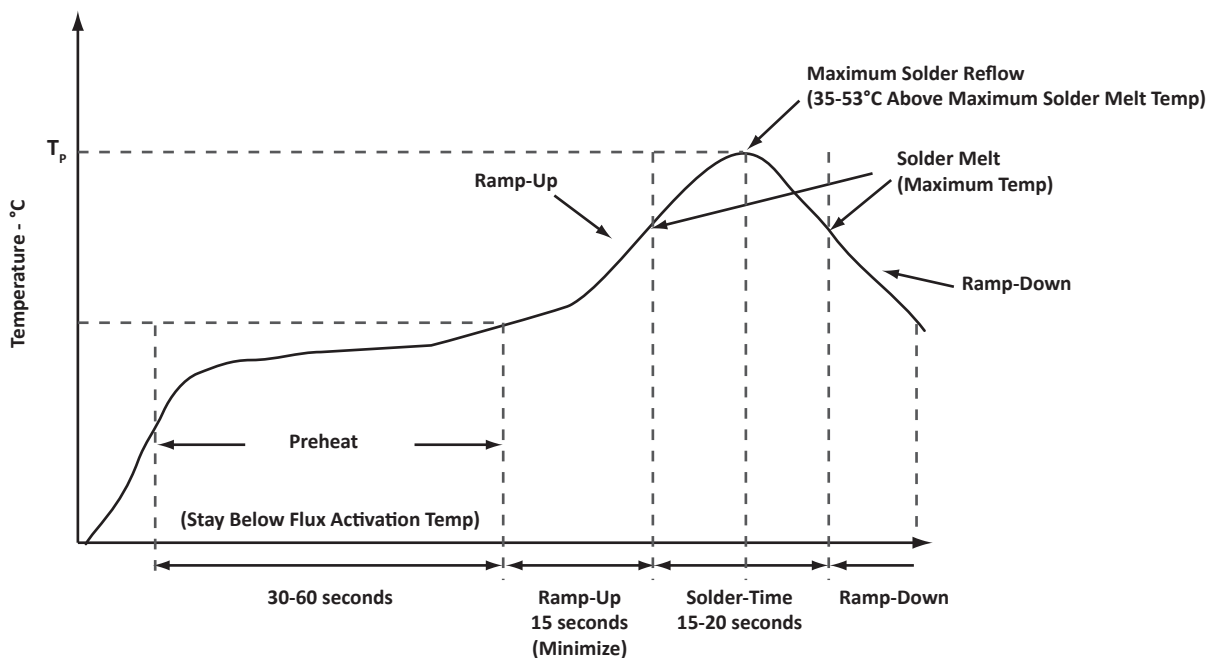
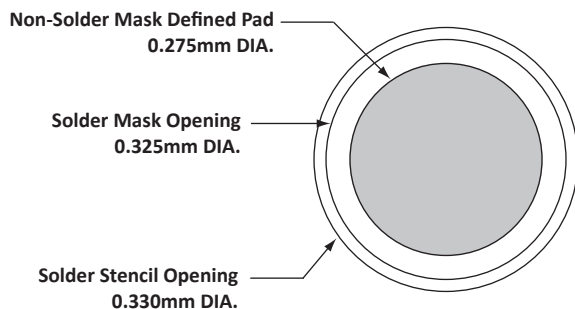
Temperature:

$T_p$  for Lead-Free (Sn/Ag/Cu): 260-270°C

$T_p$  for Tin-Lead: 240-245°C

Preheat time and temperature depends on solder paste and flux activation temperature, component size, weight, surface area and plating.

### RECOMMENDED NON-SOLDER MASK DEFINED PAD ILLUSTRATION



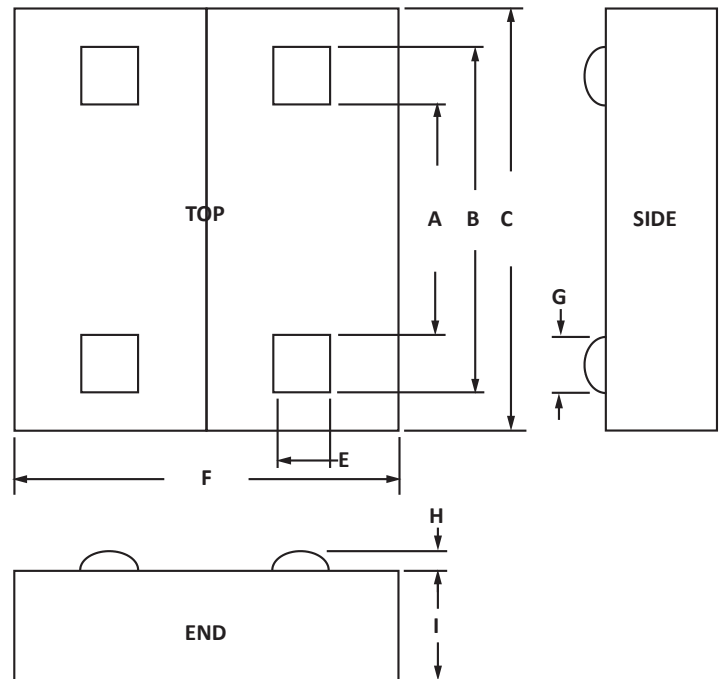
## 0404 PACKAGE INFORMATION

## OUTLINE DIMENSIONS

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.46	0.56	0.018	0.022
B	0.86		0.034	
C	0.98	1.02	0.038	0.040
E	0.15 SQ	0.15 SQ	0.006 SQ	0.006 SQ
F	0.975	1.025	0.038	0.040
G	0.15		0.006	
H	0.076	0.127	0.003	0.005
I	0.406		0.016	

## NOTES

- Controlling dimensions in inches.
- Decimal tolerance: .xxx ± 0.05mm (0.002").

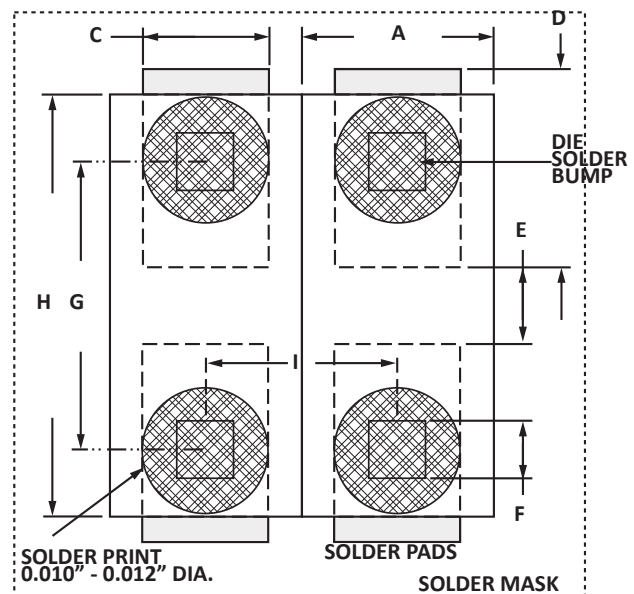


## LAYOUT DIMENSIONS

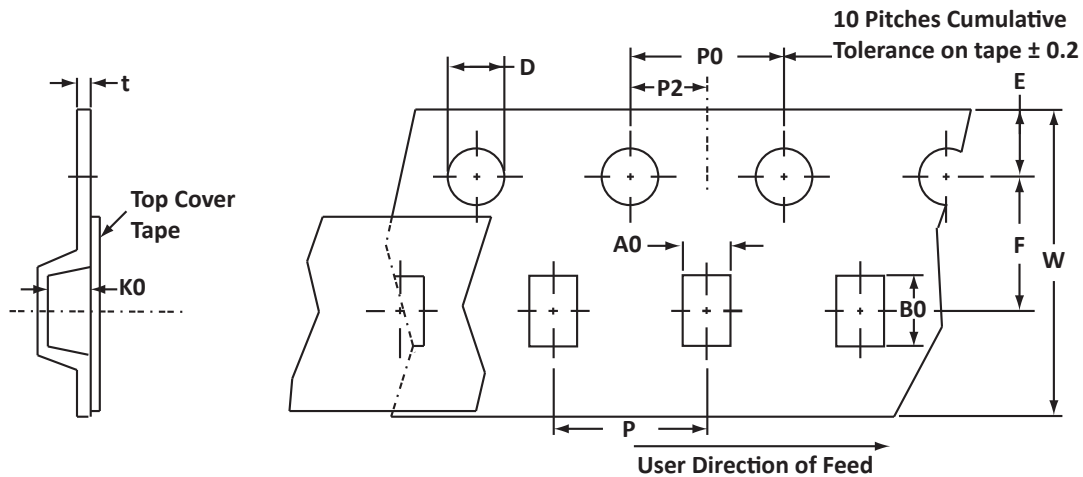
DIM	MILLIMETERS	INCHES
	NOMINAL	NOMINAL
A	0.51	0.020
C	0.30	0.012
D	0.46	0.018
E	0.20	0.008
F	0.15 SQ	0.006 SQ
G	0.71	0.028
H	0.99	0.039
I	0.51	0.020

## NOTES

- Controlling dimensions in inches.
- Decimal tolerance: .xxx ± 0.05mm (0.002").
- Preferred: Usign 0.1mm (0.004") stencil.



## TAPE AND REEL INFORMATION



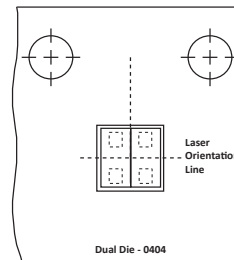
### SPECIFICATIONS

REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	Tmax
178(7")	8	0.80 ± 0.10	1.20 ± 0.10	0.70 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.20	4.00 ± 0.12	2.00 ± 0.05	2.00 ± 0.10	0.25

#### NOTES

1. Dimensions in millimeters.
2. Top view of tape. Solder bumps are face down in tape package.
3. Orientation: preferred stencil - 0.1mm (0.004").
4. Surface mount product is taped and reeled in accordance with EIA 481.
5. 8mm plastic tape: 7" Reels - 5,000.

#### TAPE & REEL ORIENTATION



Package outline, pad layout and tape specifications per document number 06022.R5 9/09.

### ORDERING INFORMATION

BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
P0404FCxxC	-LF	-T75-1	5,000	7"	n/a

This device is only available in a Lead-Free configuration.

## COMPANY INFORMATION

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### COMPANY PROFILE

In business more than 20 years, ProTek Devices™ is a privately-held company located in Tempe, Arizona, that offers a product line of transient voltage suppressors (TVS); avalanche breakdown diodes; steering diode TVS arrays and other surge suppressor component products. These TVS devices protect electronic systems from the effects of lightning, electrostatic discharge (ESD), nuclear electromagnetic pulses (NEMP), inductive switching and EMI / RFI. ProTek Devices also offers high performance interface and linear products that include analog switches; multiplexers; LED drivers; audio control ICs; RF and related high frequency products. The analog devices work in a host of consumer; industrial; automotive and other applications.

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PATENT INFORMATION: This device is patented under U.S. Patent No. Des. "D456,367S".